

**Notice of References Cited**

Application/Control No.

10/008,665

Applicant(s)/Patent Under  
Reexamination  
KALLING ET AL.

Examiner

Brian L. Mutschler

Art Unit

1753

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	W	"Table: Thermal and Physical Properties of Pure Metals", CRC Handbook of Chemistry and Physics (3rd Electronic Edition, 2000).
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.